

Annexure I

Technical Specifications

Technology	Deposition of conductive ink on variety of substrates (details listed below) followed by curing
Operations and Features	<ul style="list-style-type: none"> • Printing using conductive ink • Drilling <p>Features:</p> <ul style="list-style-type: none"> • Capable of dispensing conductive as well as flexible conductive ink • Capable of printing on standard rigid substrates as well as flexible substrates • Soldering surface mounted components using heated bed reflow technique
Types of inks	Conductive ink for rigid substrates Flexible conductive ink for flexible substrates
Types of applicable substrates	Glass reinforced epoxy laminated substrates (FR1,FR4), Fibreglass resins, ceramics, Flexible substrates like plastics, PET
Type of fixture for attachments	Quick and easy to change; preferably Magnetic Mounting
Automated Pick and Place	Not required
Minimum Print Bed Size	125mmX100mm
Compatible File Format for Software	Gerber
Connection Type	USB
Maximum Heated Bed Temperature	>220°celsius
No. of layers of printable circuit	2
Minimum Trace Width for Printing	<0.3mm
Minimum Pin-to-Pin Pitch for Printing	<0.8 mm
Supported Material for drilling	FR1
Maximum Spindle Speed for drilling	12,000 RPM (minimum)
Runout in drilling	<0.09mm
Maximum Drill bit diameter	2mm
Minimum Pin to Pin Pitch in soldering	0.5mm

